

NOTES : TRIANGLE SYMBOLS IDENTIFY NOTES ON THIS DRAWING.

↑
LABEL TEXT
ORIENTATION
DO NOT COVER IC MPN

REVISIONS				
ZONE	REV	DESCRIPTION	DATE	APPROVED
	A	PRODUCTION RELEASE	5/24/16	Kinjalk Tripathi
	B	PRODUCTION RELEASE	6/6/16	Kinjalk Tripathi
	C	PRODUCTION RELEASE	9/28/16	Kinjalk Tripathi

NOTES:

1. ALL COMPONENTS MUST BE ABLE TO WITHSTAND THE Pb-FREE ASSEMBLY PROFILES DESCRIBED IN IPC/JEDEC J-STD-020C (LATEST VERSION)
2. WORKMANSHIP SHALL CONFORM TO IPC-A-610 (LATEST REVISION) - CLASS 2 STANDARD.
3. PART SUBSTITUTION CRITERIA :-
ALL COMPONENT SUBSTITUTIONS MUST BE APPROVED AND DOCUMENTED BY FREESCALE.
4. MAXIMUM LEAD PROTRUSION ON PRIMARY AND SECONDARY SIDE OF PRINTED WIRING BOARD IS .100".
5. PLACE PRINTED SERIAL NUMBER LABEL (805-75116) WHERE SHOWN.
6. PLACE PRINTED SCHEMATIC&ASSEMBLY/REVISION LABEL (805-76618) WHERE SHOWN, WHICH MUST BE PRINTED "SCH/700-29217 REV" AND REVERSION REFER TO IT IN AGILE SYSTEM BUT NOT THE REVISION OF THIS DRAWING.
LABEL MUST SAY:
700-29217 REV_
SCH-29217 REV_
7. PLACE 4PCS BUMPERS (PN:280-76746) WHERE SHOWN IN SHADOW AREA
8. PLACE 2PCS MAC ADDRESS LABEL (PN:805-77404) WHERE SHOWN IN BLUE AREA


PRIMARY SIDE

SOLDER PROCESS	
Pb FREE	<input checked="" type="checkbox"/> YES <input type="checkbox"/> NO

975-29217	FRDM-LS1012A-PA
NEXT ASSY	USED ON
APPLICATION	

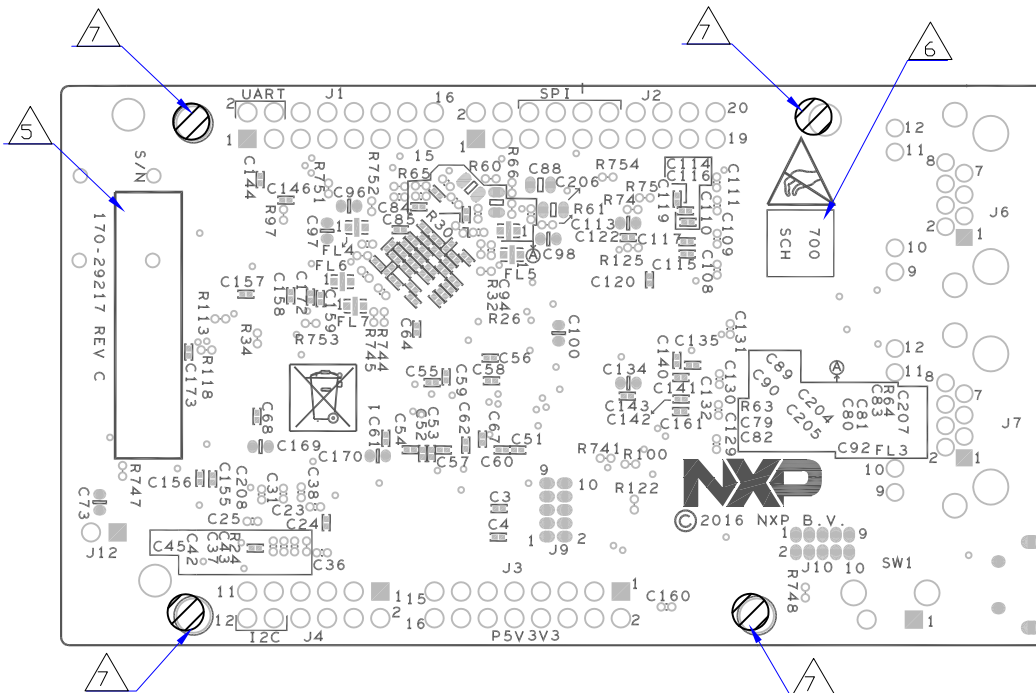
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES. TOLERANCES ARE: DECIMALS .XX ±.020 .XXX ±.010 ✓ RMS ALL MACHINED SURFACES BREAK ALL SHARP EDGES AND CORNERS, REMOVE BURRS. UNDERLINED DIM. NOT TO SCALE. THIRD ANGLE ORTHOGRAPHIC PROJECTION IS USED.	
MATERIAL	FINISH
HEAT TREAT	

PART NO. 700-29217	
THIS DOCUMENT CONTAINS INFORMATION PROPRIETARY TO FREESCALE AND SHALL NOT BE USED FOR ENGINEERING DESIGN, PROCUREMENT OR MANUFACTURE IN WHOLE OR IN PART WITHOUT THE CONSENT OF FREESCALE.	
APPROVALS	DATE
DRAWN BRIAN WANG	9/28/16
CHECKED BOBBY ZHAO	9/28/16
DESIGN ENGINEER Kinjalk Tripathi	9/28/16

		NXP semiconductor 8501 WILLIAM CANNON DRIVE AUSTIN, TEXAS 78735-8598 USA	
TITLE FRDM-LS1012A-PA PWA ASSEMBLY			
SIZE B	FILE NAME ASY-29217.DXF	DWG. NO. ASY-29217	REV C
SCALE -----	DO NOT SCALE DRAWING		SHEET 1 OF 2

NOTES : TRIANGLE SYMBOLS IDENTIFY NOTES ON THIS DRAWING.

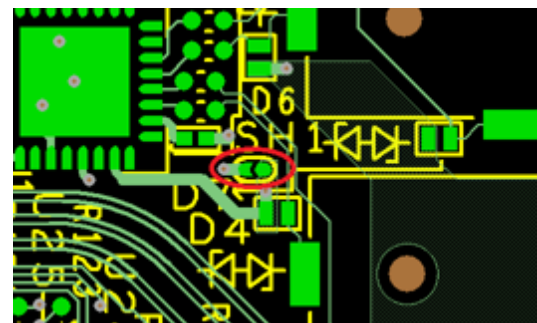
↑
LABEL TEXT
ORIENTATION
DO NOT COVER IC MPN



SECONDARY SIDE

9. PAY ATTENTION TO THE CPU SOLDERING FROM STENCIL DESIGN CONSIDERATION

10. DO BELOW REWORK: ADD A SMALL SOLDER DROP TO SHORT SH1 GND & AGND :



11. APPLY SOME DROPS GLUE (TYPE: LOCTITE 444) BETWEEN THE BODY OF TWO AUDIO CONNECTORS (211-79134, J8 & J13) AND PCB TO FIX THE PART ONTO THE BOARD AFTER SOLDERING



NXP semiconductor
6501 WILLIAM CANNON DRIVE
AUSTIN, TEXAS 78735-8588 USA

--- PUBLI (PUBLIC INFORMATION)
X FIUD (FREESCALE INTERNAL USE ONLY)
--- FCP (FREESCALE CONFIDENTIAL PROPRIETARY)

TITLE
FRDM-LS1012A-PA
PWA ASSEMBLY

SIZE	FILE NAME	DWG. NO.	REV
B	ASY-29217.DXF	ASY-29217	C

SCALE: DO NOT SCALE DRAWING SHEET 2 OF 2